



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Atty. Docket No.: BU9-99-197

2823
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Response Transmittal

In re application of: Furukawa, et al.

Serial No.: 09/599,783 ✓

Filed: 6/22/00

For: METHOD FOR ETCHING A SEMICONDUCTOR
SUBSTRATE USING GERMANIUM HARD MASK

Box Fee

Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

Transmitted herewith for filing in the above-identified Application is a:

1. Response;
2. Letter to the Draftsperson including 2 sheets of drawings; and
3. Postcard.

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I hereby certify that I am depositing the enclosed or attached correspondence with the United States Postal Service as first class mail in an envelope addressed to Box Fee, Commissioner of Patents and Trademarks, Washington, D.C. 20231,

on

May 31, 2001

Heather Clark

Name of person signing

Other Than Small Entity

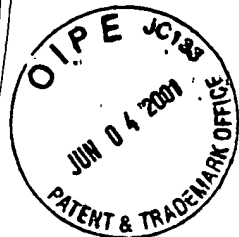
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Date: May 31, 2001

Respectfully submitted,

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Docket No. BU9-99-197

#5/Amend A
6/11/01

IN THE UNITED STATES PATENT AND
TRADEMARK OFFICE
AMENDMENT

Applicant:	Furukawa, et al.	Docket No.:	BU9-99-197
Serial No.:	09/599,783	Group Art Unit:	2823
Filed:	06/22/00	Examiner:	Eaton, K.
TITLE:	METHOD FOR ETCHING A SEMICONDUCTOR SUBSTRATE USING GERMANIUM HARD MASK		

Box Fee
The Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

Responsive to the office action dated March 26, 2001, Applicants amend the application as follows:

06/07/2001 HNDHAMM1 00000140 090456 09599783
01 FC:103 18.00 CH

I HEREBY CERTIFY THAT THE CORRESPONDENCE TO WHICH THIS STATEMENT IS AFFIXED IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE, POSTAGE PAID, AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO THE COMMISSIONER OF PATENTS AND TRADEMARKS, WASHINGTON, D.C., 20231, ON: May 31, 2001

SIGNED: Heather Clark